

No.	PCN02257	PCN Date	September 14, 2012	Effective Date	December 15, 2012
Title	Add UTAC Dongguan (UDG) as a qualified source of the BGA package				

Approval Notice

Everspin Inc. will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

Description and Purpose – Affected Products

To increase production capacity and improve flexibility in manufacturing Everspin has qualified the following products to be manufactured at UTAC DongGuan (UDG):

Configuration	Everspin Part Numbers	Package
1Mb MRAM (128Kb x 8)	MR0A08BMA35, MR0A08BCMA35, MR0D08BMA45 (Includes R suffix for part numbers shipping in Tape and Reel.)	8 x 8 mm 48 ball BGA
256Kb MRAM (32Kb x 8)	MR256A08BMA35, MR256A08BCMA35, MR256D08BMA45 (Includes R suffix for part numbers shipping in Tape and Reel.)	8 x 8 mm 48 ball BGA
16Mb MRAM (1Mb x16)	MR4A16BMA35, MR4A16BCMA35	10 x 10 mm 48 ball BGA

Material Differences

There is no effect on form, fit or function for products manufactured at UTAC DongGuan. There is no change for testing of these products. The assembly location code for UDG is G.

Contact Information

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Originator

<u>Date</u>	<u>Title</u>	<u>Name</u>
September 11, 2012	VP Marketing	Steffen Hellmold

Approval and Release

<u>Date</u>	<u>Title</u>	<u>Name</u>
September 11, 2012	VP Quality	Brad Engel